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ABSTRACT

A device embedded substrate provided with first and second connecting terminals on different surfaces, the substrate including: an electrically conductive metal block having one surface connected to the first connecting terminal, and having a dimension in a lateral direction larger than that of the electronic device; an intermediate connecting portion juxtaposed to the electronic device, including first insulation layer and wiring layers, whereby the first wiring layer is connected to the one surface of the metal block via a first conductive via; a second insulation layer which accommodates the metal block; and a third insulation layer stacked on the second insulation layer to embed the electronic device and whereon a second wiring layer is stacked, wherein the second wiring layer is connected to the first wiring layer via a second conductive via and connected to the second connecting terminal of the electronic device via a third conductive via.

